



#### **Manufacturer:**

**Epoxy Technology** 

#### **Product Name:**

EPO-TEK® 353ND High Temperature Epoxy, Heat Cure (8oz)

#### **Manufacturer Part Number:**

ET353ND-8OZ

Click here for more details on the EPO-TEK® 353ND High Temperature Epoxy, Heat Cure (8oz)



## **EPO-TEK® 353ND**

May not achieve performance properties below

**Technical Data Sheet** For Reference Only High Temperature Epoxy

Date: March 2023 Recommended Cure: 150°C / 1 Hour

Rev: XXXI No. of Components: Two

Mix Ratio by Weight: 10:1 Specific Gravity:

Part A: 1.20 Pot Life: ≤ 3 Hours Shelf Life- Bulk: Shelf Life- Syringe:

One year at room temperature Six months at -40°C

Part B: 1.02 Syringe: 1.18 Syringe: ≤ 2 Hours

150°C / 1 Minute 120°C / 5 Minutes

100°C / 10 Minutes 80°C / 30 Minutes

Minimum Alternative Cure(s):

NOTES: Container(s) should be kept closed when not in use.

- Filled systems should be stirred thoroughly before mixing and prior to use.
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   Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters
- If product crystallizes in storage, place container in warm oven until crystallization disappears.
   TOTAL MASS SHOULD NOT EXCEED 25 GRAMS

Product Description: EPO-TEK® 353ND is a two component, high temperature epoxy designed for semiconductor, hybrid, fiber optic, and medical applications. It is one of the most popular EPO-TEK® brand products, and is known throughout the world for its performance and reliability. Also available in single component frozen syringe.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptant \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:						
* Color (before cure):			Part A: Clear (Gardner < 5) Part B: Amber (Gardner < 18)			
* Consistency:		Pourable liquid				
* Viscosity (23°C) @ 50 rpm:		3	3,000 - 5,000	cPs		
Thixotropic Index:			N/A			
* Glass Transition Temp:			≥ 90	°C (E	Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expans	ion (CTE):					
	Below Tg:		54	x 10	<sup>6</sup> in/in°C	
	Above Tg:		206	x 10	<sup>6</sup> in/in°C	
Shore D Hardness:			85			
Lap Shear @ 23°C:			> 2,000	psi		
Die Shear @ 23°C:			≥ 15	Kg	5,334 psi	
Degradation Temp:			412	°C		
Weight Loss:						
	@ 200°C:		0.22	%		
	@ 250°C:		0.39	%		
	@ 300°C:		0.87	%		
Suggested Operating Temperature:				,	ntermittent)	
Storage Modulus:			508,298	psi		
Ion Content:		Cl <sup>-</sup> :	329 ppm			
		$NH_4^+$ :		K+:	5 ppm	
* Particle Size:			N/A			
ELECTRICAL AND THERMAL	. PROPERTI	ES:				
Thermal Conductivity:			N/A			
Volume Resistivity @ 23°C:		$\geq 1.8 \times 10^{13}$		Ohm	-cm	
Dielectric Constant (1KHz):		3.17				
Dissipation Factor (1KHz):			0.005			
OPTICAL PROPERTIES @ 23°C:				nm		
Spectral Transmission:		≥ 50% @ 550				
			@ 1100-1600	nm		
Refractive Index (uncured):		≥ 98%	6 @ 800-1000 1.5694 @589	nm nm		
incliactive muex (uncureu).			1.3034 @369	11111		

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## Contact the professionals at Fiber Optic Center for a quote or to get more details.





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# **EPO-TEK® 353ND**

Technical Data Sheet For Reference Only High Temperature Epoxy

## **EPO-TEK® 353ND Advantages & Suggested Application Notes:**

- Reasonable pot-life that allows for low temperature curing to be realized. It has an amber color change upon cure.
- Passes NASA low outgassing standard ASTM E595 with proper cure http://outgassing.nasa.gov/
- Semiconductor suggested applications: wafer-wafer bonding of CSP; fabrication of MEMs devices; flip chip underfill.
- Hybrid suggested applications: providing near hermetic seals and UHV seals in sensor devices, resisting high temperature packaging.
  - o Down-Hole petrochemical fiber optic sensors, resisting >200°C field conditions.
- Fiber optic adhesive designed to meet Telecordia 1221 suggested applications:
  - Sealing fiber into ferrules, transmitting light in the optical pathway from 800- 1550 nm range.
  - Fiber component packaging; adhesive for active alignment of optics, environmental seal of opto-package, V-groove arrays.
- Electronics Assembly suggested applications:
  - Used as dielectric layer in the fabrication of capacitors; laminating PZT ferroelectrics found in ultrasound or ink-jetting devices.
  - Impregnating and insulating copper coil windings in motors and inductor coils. Bonding ferrite cores and magnets.
  - Structural grade epoxy found in hard-disk drive devices; bonding of SST metals, kapton, and magnets.

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Contact the professionals at Fiber Optic Center for a quote or to get more details.